TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

2SK2718

DC-DC Converter and Motor Drive Applications

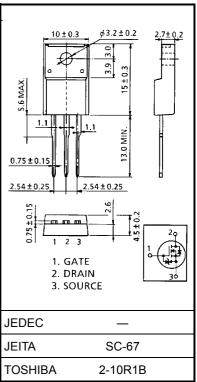
Unit: mm

• Low drain-source ON resistance : RDS (ON) = 5.6Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 2.0 S$ (typ.)

• Low leakage current : $IDSS = 100 \mu A (max) (VDS = 720 V)$ • Enhancement-mode : $V_{th} = 2.0 \sim 4.0 V (V_{DS} = 10 V, I_D = 1 mA)$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	900	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	2.5	Α	
	Pulse (Note 1)	I _{DP}	7.5	Α	
Drain power dissipation	n (Tc = 25°C)	P_{D}	40	W	
Single pulse avalanche energy (Note 2)		E _{AS}	216	mJ	
Avalanche current		I _{AR}	2.5	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	4.0	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

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Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 63.4 mH, R_G = 25 Ω , I_{AR} = 2.5 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

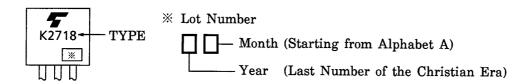
Electrical Characteristics (Ta = 25°C)

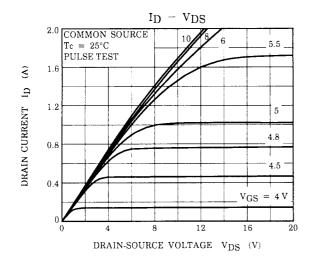
Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V _(BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V		_	100	μΑ
Drain-source bro	eakdown voltage	V _{(BR)DSS}	I_D = 10 mA, V_{GS} = 0 V	900	_	_	V
Gate threshold v	oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Of	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 1.5 A	_	5.6	6.4	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 20 V, I _D = 1.5 A	1.0	2.0	_	S
Input capacitanc	е	C _{iss}		_	510	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	10	_	pF
Output capacitance		C _{oss}			55	_	
Switching time	Rise time	t _r	$V_{GS} = 10V$ $V_{GS} = 1.5A$ V_{OUT} $V_{DD} = 400V$	_	20	_	
	Turn-on time	t _{on}		_	60		ns
	Fall time	t _f		_	40	_	115
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\rm W} = 10 \mu \rm s$	_	115	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	21	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 2.5 \text{ A}$		11	_	nC
Gate-drain ("miller") Charge		Q_{gd}			10	_	

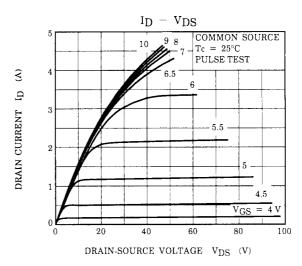
Source-Drain Ratings and Characteristics (Ta = 25°C)

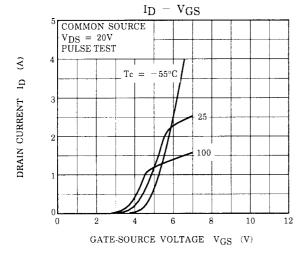
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	-	_	_	2.5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	7.5	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 2.5 A, V _{GS} = 0 V	_	_	-2.0	V
Reverse recovery time	t _{rr}	I _{DR} = 2.5 A, V _{GS} = 0 V	1	960	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 100 Å / μs	_	5.3	_	μC

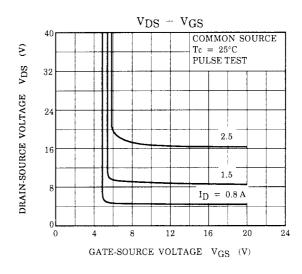
Marking

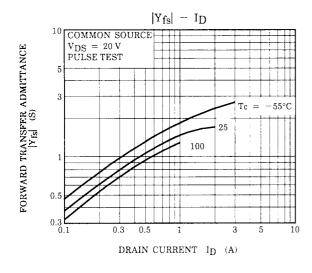


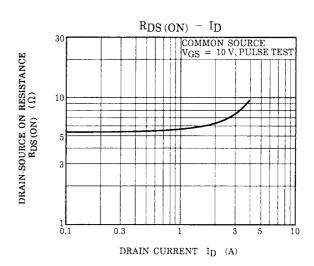




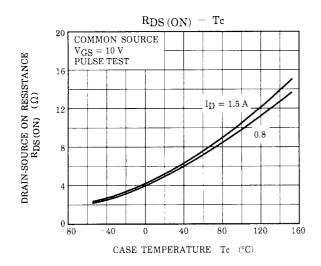


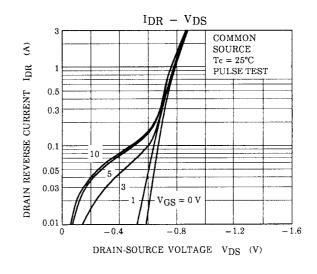


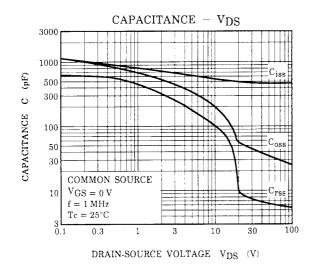


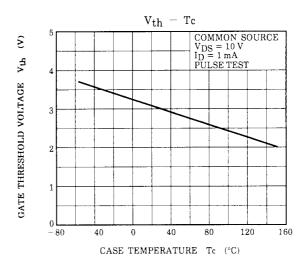


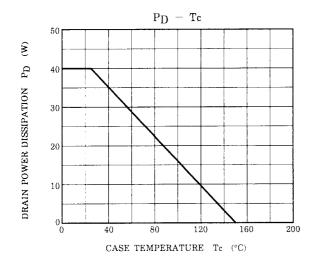
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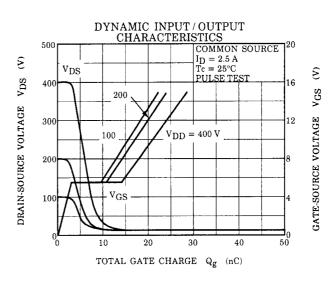




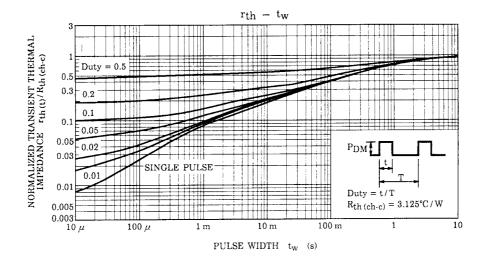


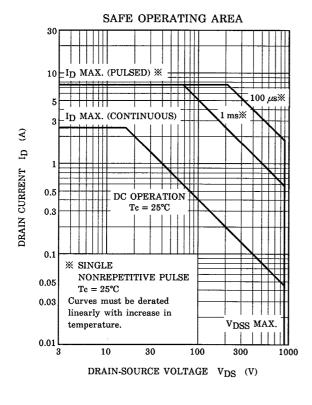


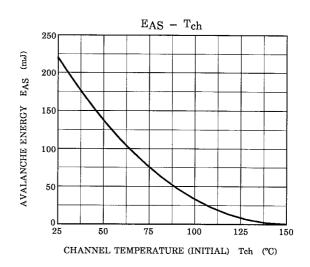


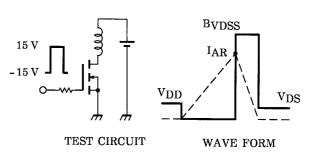


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$$R_G = 25 \Omega$$

 $V_{DD} = 90 \text{ V}, L = 63.4 \text{ mH}$ $EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD}\right)$

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